A method for manufacturing a multi-layer (New) ceramic electronic part, said multi-layer ceramic electronic part comprising a laminated body in which a ceramic layer and internal electrodes are laminated on one another, external electrodes provided at end portions of the laminated body, the internal electrodes opposing each other and reaching to one of at least a pair of edges of the ceramic layer, thereby leading out the internal electrodes to an end surface of the laminated body and connecting the internal electrodes to the external electrodes, and pillar like eramic portions which are continuous in a direction of thickness of a conductor film forming the external electrodes and scattered in the conductor film, said method comprising the steps of:

preparing an unbaked laminated body comprising a ceramic layer and internal electrodes laminated on one another;

applying and drying a conductor paste, into which is added a material common with a ceramic forming the ceramic layer of the laminated body, on edge portions of the unbaked laminated body;

forming external electrodes in contact with the internal electrodes at end surfaces of the laminated body;

baking the laminated body; and
completing the multi-layer ceramic electronic

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- 8. (New) The method of Claim 7, additionally comprising the step of providing pillar-like ceramic portions which are scattered in a conductor film forming the external electrodes and continuous in a direction of thickness of the conductor film.
- 9. (New) The method of Claim 7, additionally comprising the step of forming the ceramic portions of the external electrodes so that they are continuous from an inner surface of the conductor film of the external electrodes, where it closely contacts with a surface of the laminated body, up to an outer surface thereof.
- 10. (New) The method of Claim 7, additionally comprising the step of forming the conductor film of at least one metal selected from the group consisting of Ni, Cu, Ag, Pd and an Ag-Pd alloy.